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|----|----------|--|---|
| 30 | 22 | ((top or protective or sheet or template or lid or cover) same (glue or seal\$4 or adhesive\$5) same (photosensitive or photoreactive or photoresist) same pattern\$4 same (support or spacer or structure)) and ((top or protective or lid or sheet or template or cover) same (transmissive or transparent or translucent) same (die or circuit\$4 or function\$4 or imag\$4 or wafer)) and (encapsulat\$4 or encapsulant or packag\$3)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB |
| 31 | 12 | ((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5))) and ((cover or lid or encapsulant) same (transparent or transmissive or transmitting) same (support or (spac\$4 near9 structure) or spacer or seal) same (photosensitive or photocur\$4 or photoresist or resist) same (outer or peripher\$4 or circumferen\$4)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB |

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|----|------|---|---|
| 32 | 12 | ((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5))) and ((cover or lid or encapsulant or template) same (transparent or transmissive or transmitting) same (support or (spac\$4 near9 structure) or spacer or seal) same (photosensitive or photocur\$4 or photoresist or resist) same (outer or peripher\$4 or circumferen\$4)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB |